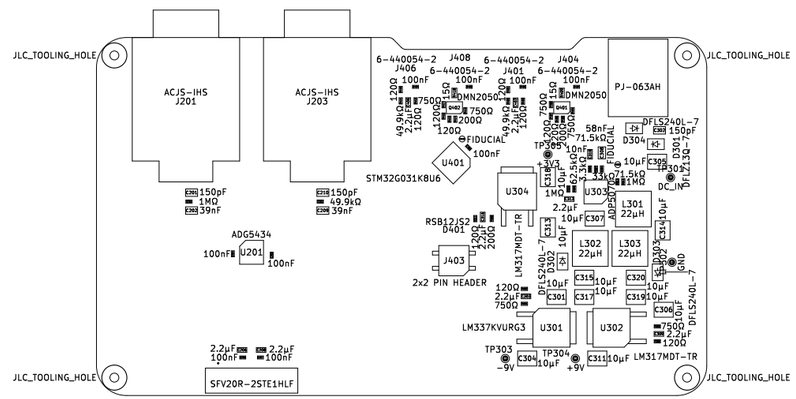
REVISION HISTORY	
Rev. A	INITIAL RELEASE



BOARD CHARACTERISTICS

Copper Layer Count:	6	Board Thickness:	1.6000 mm
Board overall dimensions:	102.3000 mm x 60.0000 mm		
Min track/spacing:	0.0900 mm / 0.0900 mm	Min hole diameter:	0.2500 mm
Copper Finish:	ENIG	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Green	3.3	0
F.Cu (Signal)	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
In1.Cu (Ground)	copper		0.0152 mm		1	0
Dielectric	core	Copper	0.5548 mm	#D2960FFF	4.5	0.02
In2.Cu (Signal)	copper		0.0152 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
In3.Cu (Ground)	copper		0.035 mm		1	0
Dielectric	core	FR4	0.5548 mm	Not specified	4.5	0.02
In4.Cu (Power)	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1 mm	Not specified	4.5	0.02
B.Cu (Ground)	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

NOTES: UNLESS OTHERWISE SPECIFIED

1: MANUFACTURE TO IPC CLASS 2

TITLE	DRAWN BY	DOCUMENT TYPE	DOCUMENT STATUS
1590N1 BASEBOARD – PCBA	AIR	PCB	RELEASED
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			SHEET: 1/1

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